

# LNPTM STAT-KONTM COMPOUND DX04403

PDX-D-04403

## **DESCRIPTION**

LNP STAT-KON DX04403 compound is based on Polycarbonate (PC) resin containing 8% carbon fiber. Added features of this grade include: Electrically Conductive, Flame Retardant.

GENERAL INFORMATION	
Features	Flame Retardant, Electrically Conductive, Low ionics/Outgassing/Liquid particle count, Carbon fiber filled, High stiffness/Strength
Fillers	Carbon Fiber
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY	
Electrical and Electronics	Electronic Components	
Industrial	Material Handling	

# **TYPICAL PROPERTY VALUES**

Revision 20230607

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, break	90	MPa	ASTM D638
Tensile Stress, brk, Type I, 5 mm/min	90	MPa	ASTM D638
Tensile Strain, break	6.3	%	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	6.3	%	ASTM D638
Flexural Stress	142	MPa	ASTM D790
Flexural Stress, brk, 1.3 mm/min, 50 mm span	142	MPa	ASTM D790
IMPACT (1)			
Izod Impact, unnotched, 23°C	576	J/m	ASTM D4812
Izod Impact, notched, 23°C	64	J/m	ASTM D256
THERMAL (1)			
HDT, 0.45 MPa, 3.2 mm, unannealed	143	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	140	°C	ASTM D648
Relative Temp Index, Elec <sup>(2)</sup>	80	°C	UL 746B
Relative Temp Index, Mech w/impact (2)	80	°C	UL 746B
Relative Temp Index, Mech w/o impact (2)	80	°C	UL 746B
PHYSICAL (1)			
Density	1.253	g/cm³	ASTM D792
Mold Shrinkage, flow, 24 hrs <sup>(3)</sup>	0.3	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs <sup>(3)</sup>	0.4	%	ASTM D955
ELECTRICAL (1)			
Surface Resistivity (4)	1.E+06 – 1.E+09	Ω	ASTM D257



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
FLAME CHARACTERISTICS (2)			
UL Yellow Card Link	E121562-101283799	-	-
UL Recognized, 94V-0 Flame Class Rating	0.9	mm	UL 94
INJECTION MOLDING (5)			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	305 – 325	°C	
Front - Zone 3 Temperature	320 – 330	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	295 – 305	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Measurement meets requirements as specified in ASTM D4496.
- (5) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

#### MORE INFORMATION

For curve data and CAE cards, please visit and register at https://materialfinder.sabic-specialties.com

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